



Product Change Notification

Change Notification #: 116686 - 00
Change Title: Intel® Server Chassis H2204XXLRE,
Intel® Server Chassis H2204XXNPS,
Intel® Server Chassis H2216XXKR2,
Intel® Server Chassis H2216XXLR2,
Intel® Server Chassis H2224XXKR2,
Intel® Server Chassis H2224XXLR2,
Intel® Server Chassis H2224XXLR3,
Intel® Server Chassis H2224XXNPS,
Intel® Server Chassis H2312XXKR2,
Intel® Server Chassis H2312XXLR2,
Intel® Server Chassis H2312XXLR3,
Intel® Server Chassis H2312XXNPS,
PCN 116686-00, Label, System Outer Box
Stacking Logo Update
Date of Publication: January 11, 2019

Key Characteristics of the Change:

Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material*:	January 11, 2019
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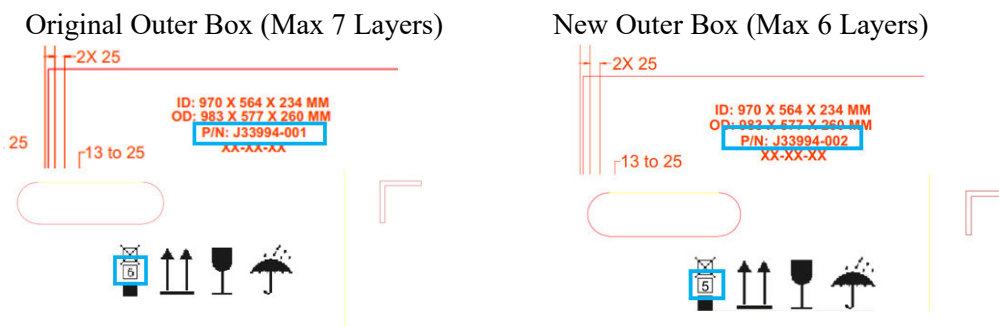
** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel*

Description of Change to the Customer:

Intel is updating the System Outer Box Stacking Logo for the packaging of the Intel Server Chassis listed in Products Affected Table below.

The Maximum Stacking logo in the packaging is changing from 7 Layers of Boxes per Pallet to a Maximum Stacking of 6 Layers of Boxes per Pallet to reduce the risk of package damage while stored or in transit.

Customers can identify the differences in the logo from the images below.



Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications. For that reason Intel recommends that the customer perform a standard level of evaluation.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre TA#	Post TA#
H2216XXKR2	933688	H20866-015	H20866-016
H2312XXKR2	933689	H20865-015	H20865-016
H2312XXLR2	942352	J17277-009	J17277-010
H2216XXLR2	942353	H95607-009	H95607-010
H2224XXKR2	943478	H70096-011	H70096-012
H2224XXLR2	943577	H96144-008	H96144-009
H2224XXLR3	948907	J57870-004	J57870-005
H2312XXLR3	954487	J57869-004	J57869-005
H2204XXLRE	957322	J32925-008	J32925-009
H2312XXNPS	976841	J92610-002	J92610-003
H2224XXNPS	976842	J92611-001	J92611-002
H2204XXNPS	976843	J92613-002	J92613-003

PCN Revision History:

Date of Revision:

January 11, 2019

Revision Number:

00

Reason:

Originally Published PCN



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The products described in this document may contain design defects or errors known as errata which may cause the product to deviate from published specifications. Current characterized errata are available on request.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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